

# SOT1098-1

plastic low profile fine-pitch ball grid array package; 268 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFPGA268
<b>Package type industry code</b>	LFPGA268
<b>Package style descriptive code</b>	LFPGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	17-11-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	16.8	-	17	17.2	mm
E	package width	16.8	-	17	17.2	mm
A	seated height	1.5	-	1.62	1.7	mm
A <sub>2</sub>	package height	1.2	-	1.26	1.3	mm
n <sub>2</sub>	actual quantity of termination	-	-	268	-	



## 2. Package outline

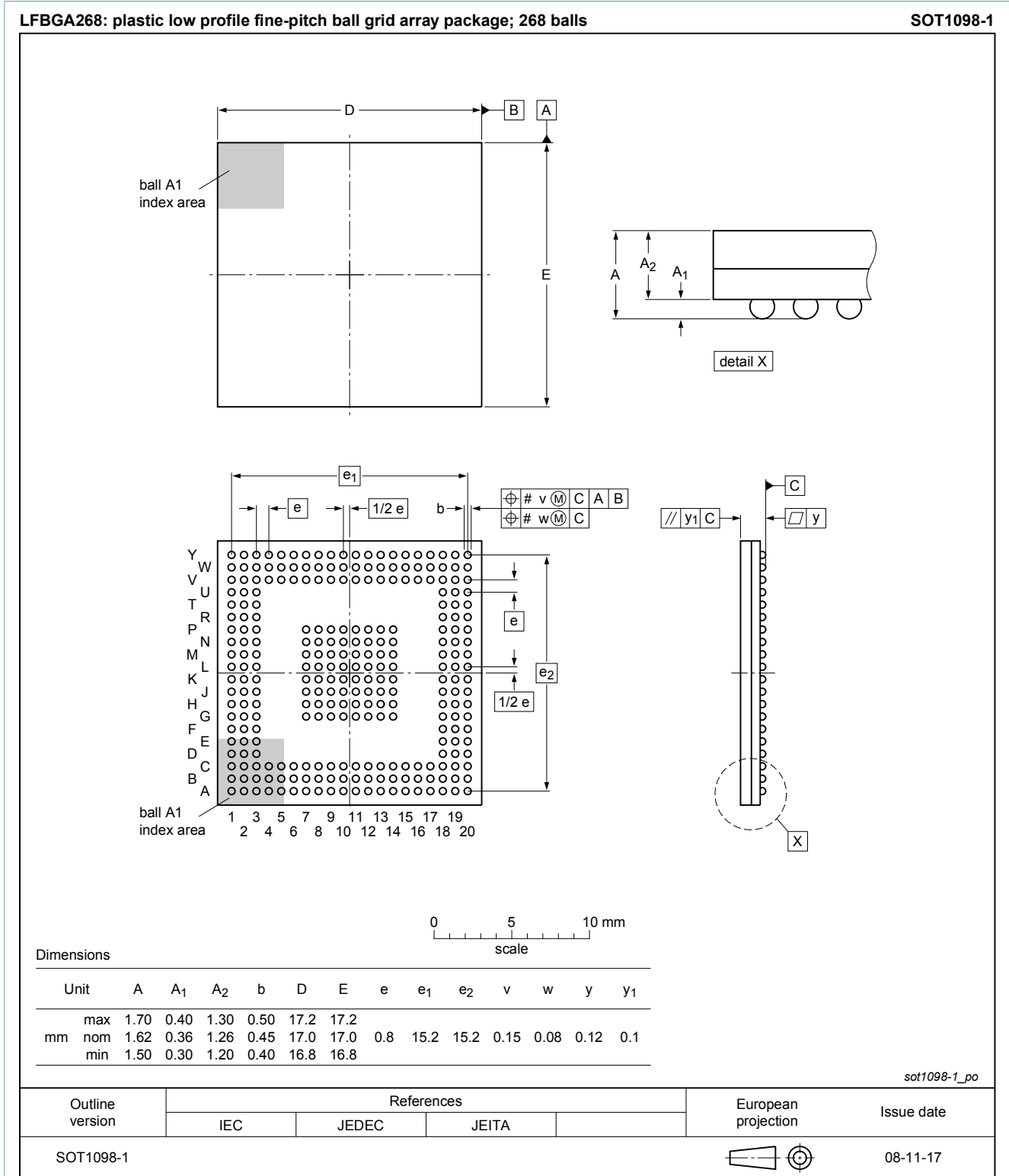


Fig. 1. Package outline LFPGA268 (SOT1098-1)

### 3. Legal information

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